

Power MOSFET

■ GENERAL DESCRIPTION

The XP162A12A6PR is a P-channel Power MOSFET with low on-state resistance and ultra high-speed switching characteristics. Because high-speed switching is possible, the IC can be efficiently set thereby saving energy. A gate protect diode is built-in to prevent static damage. The small SOT-89 package makes high density mounting possible.

■ APPLICATIONS

- Notebook PCs
- Cellular and portable phones
- On-board power supplies
- Li-ion battery systems

■ FEATURES

Low On-State Resistance : $R_{ds(on)} = 0.17\Omega @ V_{gs} = -4.5V$
: $R_{ds(on)} = 0.3\Omega @ V_{gs} = -2.5V$

Ultra High-Speed Switching

Driving Voltage : $-2.5V$

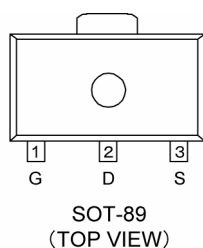
Gate Protect Diode Built-in

P-Channel Power MOSFET

DMOS Structure

Small Package : SOT-89

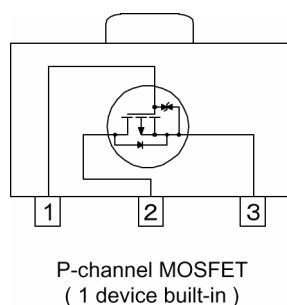
■ PIN CONFIGURATION



■ PIN ASSIGNMENT

PIN NUMBER	PIN NAME	FUNCTION
1	G	Gate
2	D	Drain
3	S	Source

■ EQUIVALENT CIRCUIT



■ ABSOLUTE MAXIMUM RATINGS

$T_a = 25^\circ C$

PARAMETER	SYMBOL	RATINGS	UNITS
Drain-Source Voltage	V_{ds}	-20	V
Gate-Source Voltage	V_{gs}	± 12	V
Drain Current (DC)	I_d	-2.5	A
Drain Current (Pulse)	I_{dp}	-10	A
Reverse Drain Current	I_{dr}	-2.5	A
Channel Power Dissipation *	P_d	2	W
Channel Temperature	T_{ch}	150	$^\circ C$
Storage Temperature Range	T_{stg}	-55~150	$^\circ C$

* When implemented on a ceramic PCB

ELECTRICAL CHARACTERISTICS

DC Characteristics

Ta = 25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain Cut-Off Current	I _{dss}	V _{ds} = -20V, V _{gs} = 0V	-	-	-10	μA
Gate-Source Leak Current	I _{gss}	V _{gs} = ±12V, V _{ds} = 0V	-	-	±10	μA
Gate-Source Cut-Off Voltage	V _{gs(off)}	I _d = -1mA, V _{ds} = -10V	-0.5	-	-1.2	V
Drain-Source On-State Resistance*1	R _{ds(on)}	I _d = -1.5A, V _{gs} = -4.5V	-	0.13	0.17	Ω
		I _d = -1.5A, V _{gs} = -2.5V	-	0.22	0.30	Ω
Forward Transfer Admittance*1	Y _{fs}	I _d = -1.5A, V _{ds} = -10V	-	4	-	S
Body Drain Diode Forward Voltage	V _f	I _f = -2.5A, V _{gs} = 0V	-	-0.85	-1.1	V

*1 Effective during pulse test.

Dynamic Characteristics

Ta = 25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Input Capacitance	C _{iss}	V _{ds} = -10V, V _{gs} =0V f= 1MHz	-	310	-	pF
Output Capacitance	C _{oss}		-	200	-	pF
Feedback Capacitance	C _{rss}		-	90	-	pF

Switching Characteristics

Ta = 25°C

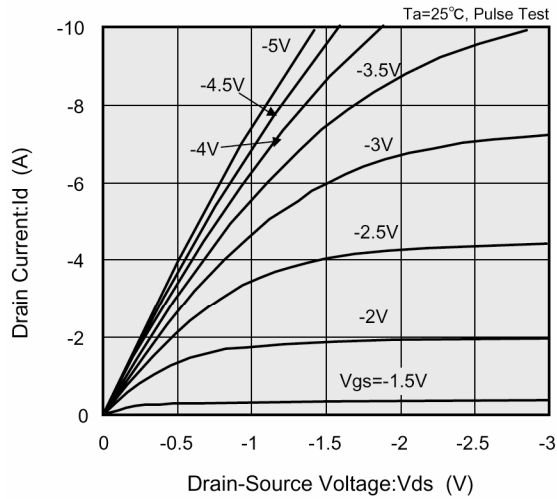
PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-On Delay Time	t _{d (on)}	V _{gs} = -5V, I _d = -1.5A V _{dd} = -10V	-	5	-	ns
Rise Time	t _r		-	15	-	ns
Turn-Off Delay Time	t _{d (off)}		-	55	-	ns
Fall Time	t _f		-	55	-	ns

Thermal Characteristics

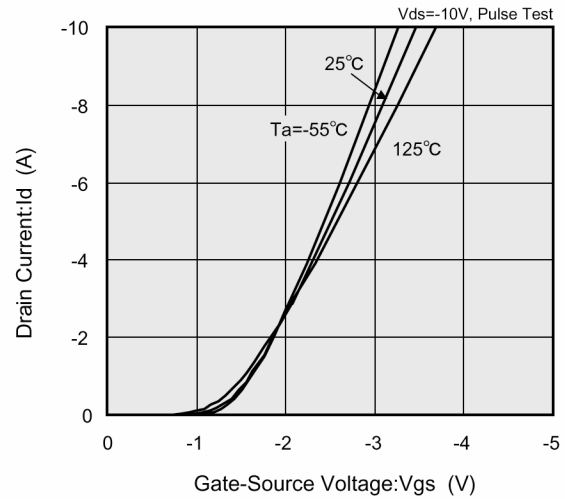
PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal Resistance (Channel-Ambience)	R _{th (ch-a)}	Implement on a ceramic PCB	-	62.5	-	°C/W

TYPICAL PERFORMANCE CHARACTERISTICS

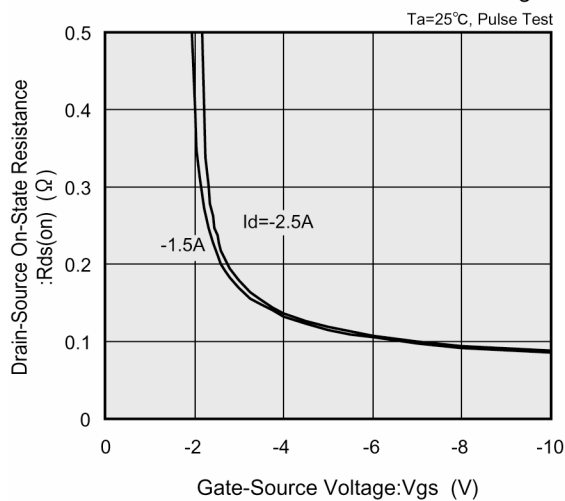
(1) Drain Current vs. Drain-Source Voltage



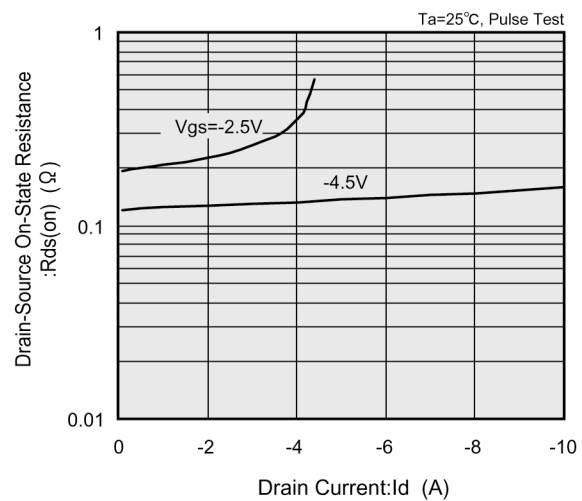
(2) Drain Current vs. Gate-Source Voltage



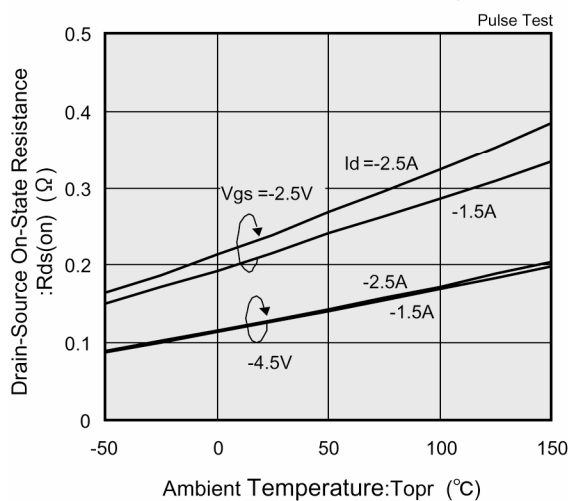
(3) Drain-Source On-State Resistance vs. Gate-Source Voltage



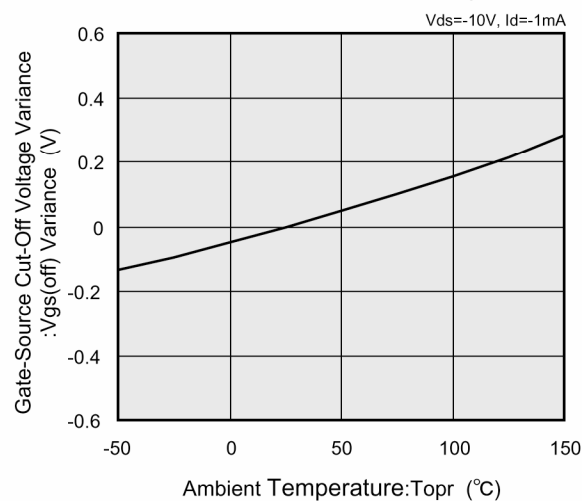
(4) Drain-Source On-State Resistance vs. Drain Current



(5) Drain-Source On-State Resistance vs. Ambient Temperature

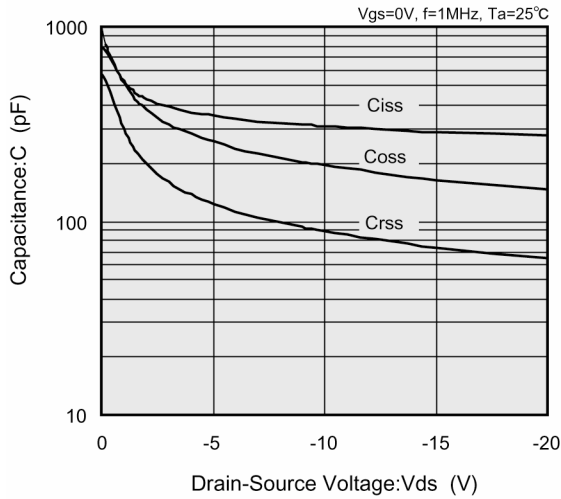


(6) Gate-Source Cut-Off Voltage Variance vs. Ambient Temperature

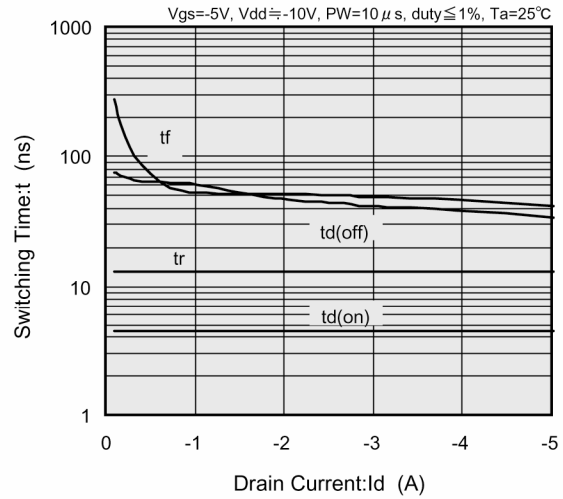


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

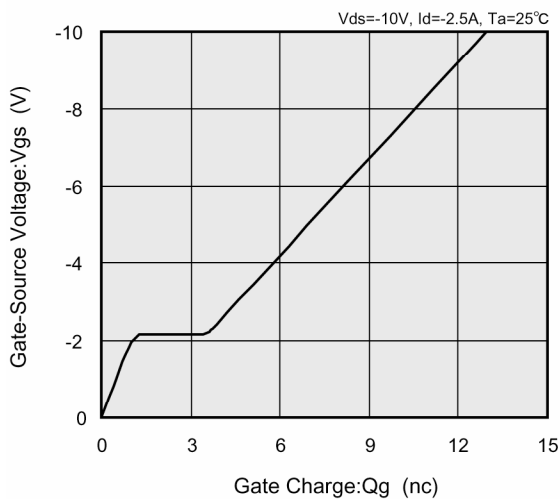
(7) Capacitance vs. Drain-Source Voltage



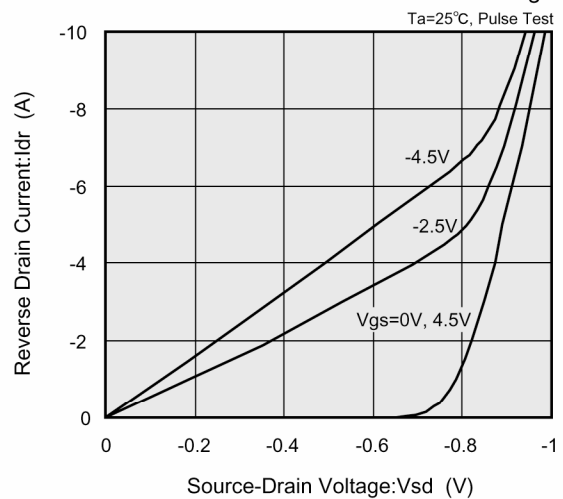
(8) Switching Time vs. Drain Current



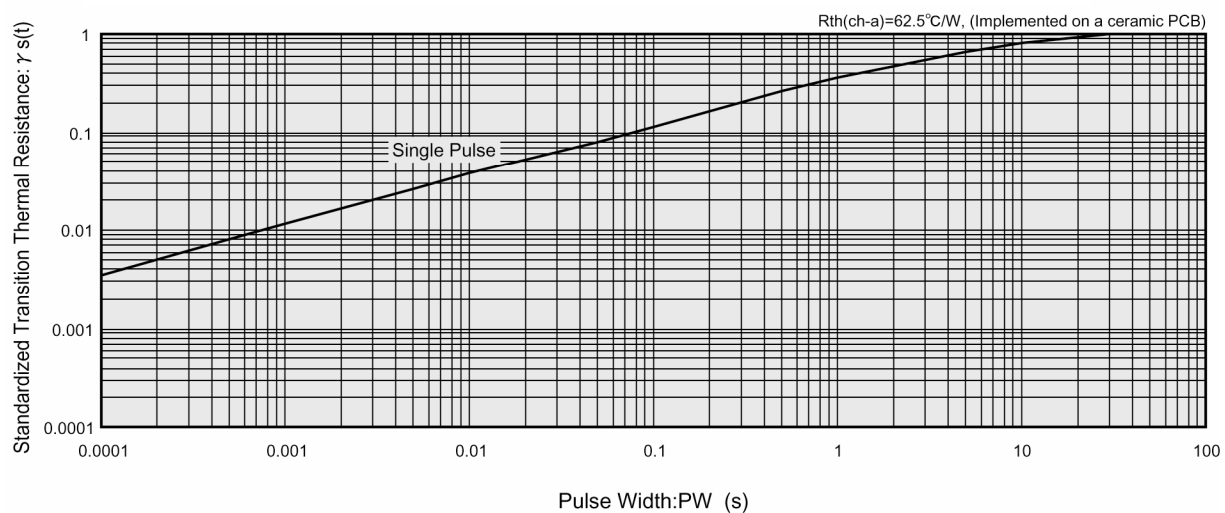
(9) Gate-Source Voltage vs. Gate Charge



(10) Reverse Drain Current vs. Source-Drain Voltage



(11) Standardized transition Thermal Resistance vs. Pulse Width



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